

FCH067N65S3-VB Datasheet

N-Channel 650V (D-S) Super Junction Power MOSFET

PRODUCT SUMMA	ARY	
V _{DS} (V) at T _J max.	650)
R _{DS(on)} at 25 °C (Ω)	$V_{GS} = 10 \text{ V}$	0.075

FEATURES

- ullet Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)

APPLICATIONS

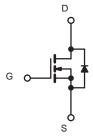
- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
 - Fluorescent ballast lighting







Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C :	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	650	V	
Gate-Source Voltage			V_{GS}	± 30]	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I _D	36		
		T _C = 100 °C		22	Α	
Pulsed Drain Current ^a			I _{DM}	108		
Linear Derating Factor				1.67	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	1400	mJ	
Maximum Power Dissipation			P_{D}	210	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		d\//d+	50	1//20	
Reverse Diode dV/dt d			dV/dt	15	V/ns	
Soldering Recommendations (Peak Temperature) c	for	10 s		260	°C	

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=100$ V, starting $T_J=25$ °C, L = 30mH, $R_g=25$ Ω , $I_{AS}=13A$.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



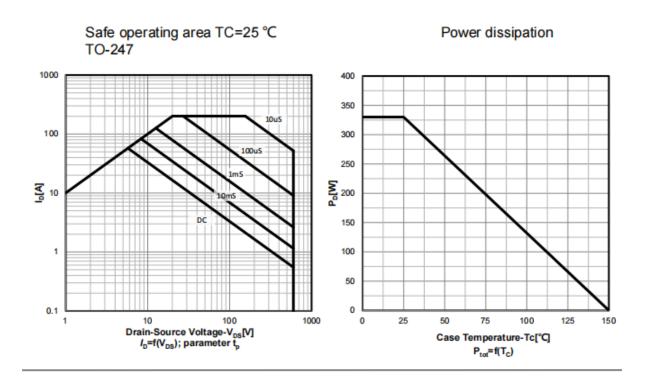
THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.38	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 1 mA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	-	4.5	V
			V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I_{GSS}		V _{GS} = ± 30 V	-	-	± 1	μA
			= 650V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}		/, V _{GS} = 0 V, T _J = 125 °C	-	-	100	μΑ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =12A	-	0.075	-	Ω
Forward Transconductance	9fs	V _{DS} = 30 V, I _D = 12A		-	5.6	-	S
Dynamic					l	ı	
Input Capacitance	C _{iss}	$V_{GS} = 0 V$,		-	3900	-	pF
Output Capacitance	Coss	1	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$		330	-	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		1	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	63	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-	
Total Gate Charge	Qg			-	60	-	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$	1	39	-	nC
Gate-Drain Charge	Q _{gd}	1		-	4 7	-	
Turn-On Delay Time	t _{d(on)}			-	18	25	
Rise Time	t _r	$V_{DD} = 520 \text{ V}, I_D = 20\text{A},$		ı	24	55	ns
Turn-Off Delay Time	t _{d(off)}			ı	8 0	-	
Fall Time	t _f	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		-	1 2	-	
Gate Input Resistance	R_{g}	f = 1 MHz, open drain		-	0.8	-	Ω
Drain-Source Body Diode Characteristic	S						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	36	_
Pulsed Diode Forward Current	I _{SM}			-	-	108	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 8 A, V _{GS} = 0 V	-	-	1.5	V
Reverse Recovery Time	t _{rr}	-		-	520	-	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 8 A, dl/dt = 100 A/μs, V _R = 400 V		-	5.8	_	μC
Reverse Recovery Current	I _{RRM}				4 5		A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .





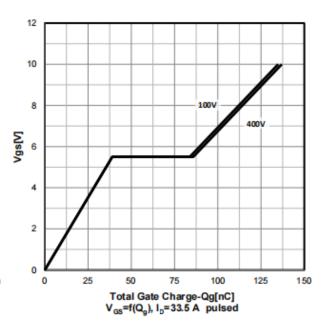
Typ. output characteristics T_i =25 $^{\circ}$ C Transfer characteristics 300 300 25°C . I_D, Drain Current [A] Drain Current [A] 200 150°C -0 5 10 0 15 20 0 2 10 12 V_{GS}, Gate-Source Voltage [V] V_{DS}, Drain to Source Voltage [V]



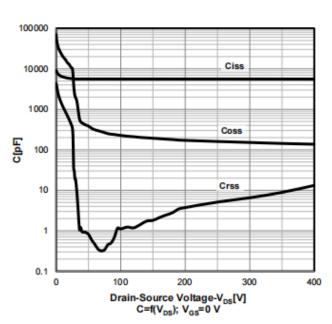
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I_D[A]
R_{DS}(on)=f(I_D); parameter: V_{GS}

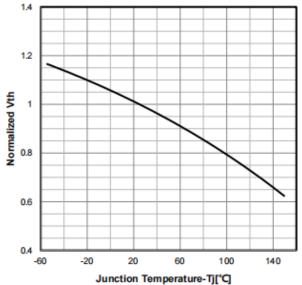
Typ. gate charge characteristics



Typ. capacitances

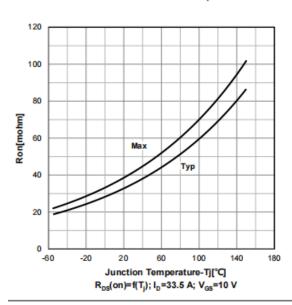


Normalized $V_{\text{GS(th)}}$ characteristics

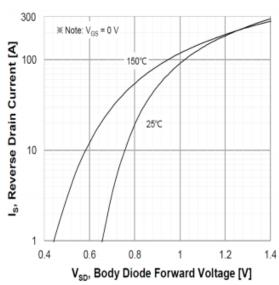




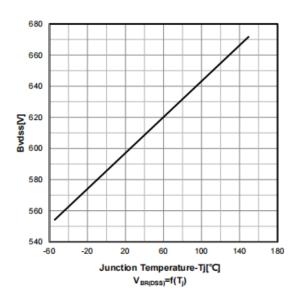
On-resistance vs temperature



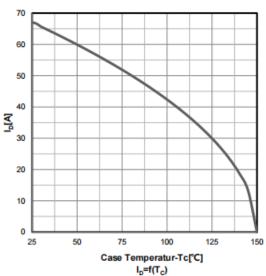
Forward characteristics of reverse diode



Drain-source breakdown voltage



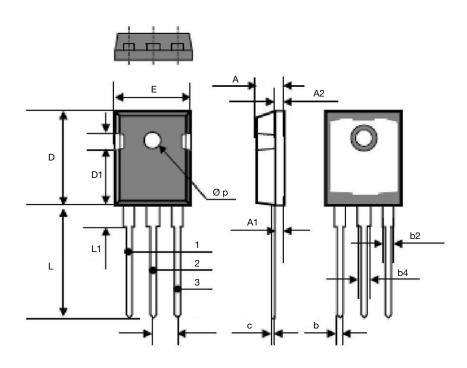
Drain current vs temperature



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TO-247



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61	0.61 BSC		0.024 BSC	
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46	BSC	0.215 BSC		
Е	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øр	3.51	3.66	0.138	0.144	



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